-3.3 V / -5 V Triple ECL Input to LVPECL Output Translator

Description

The MC100LVEL90 is a triple ECL to LVPECL translator. The device receives either -3.3~V or -5~V differential ECL signals, determined by the $V_{\rm EE}$ supply level, and translates them to +3.3~V differential LVPECL output signals.

To accomplish the level translation, the LVEL90 requires three power rails. The V_{CC} supply should be connected to the positive supply, and the V_{EE} pin should be connected to the negative power supply. The GND pins, as expected, are connected to the system ground plane. Both V_{EE} and V_{CC} should be bypassed to ground via 0.01 μF capacitors.

Under open input conditions, the \overline{D} input will be biased at $V_{EE}/2$ and the D input will be pulled to V_{EE} . This condition will force the Q output to a LOW, ensuring stability.

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 μF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

Features

- 500 ps Propagation Delays
- ESD Protection: > 2 kV HBM, > 200 V MM
- The 100 Series Contains Temperature Compensation
- Operating Range: V_{CC} = 3.0 V to 3.8 V;
 V_{EE} = -3.0 V to -5.5 V; GND = 0 V
- Internal Input Pulldown Resistors
- Q Output will Default LOW with Inputs Open or at V_{EE}
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity: Level 3 (Pb-Free)
 For Additional Information, see Application Note <u>AND8003/D</u>
- Flammability Rating: UL 94 V-0 @ 0.125 in, Oxygen Index: 28 to 34
- Transistor Count = 261 devices
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant



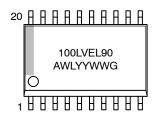
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SOIC-20 WB DW SUFFIX CASE 751D

MARKING DIAGRAM*



A = Assembly Location
WL = Wafer Lot

YY = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
MC100LVEL90DWG	SOIC-20 WB (Pb-Free)	38 Units/Tube
MC100LVEL90DWR2G	SOIC-20 WB (Pb-Free)	1000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}For additional marking information, refer to Application Note <u>AND8002/D</u>.

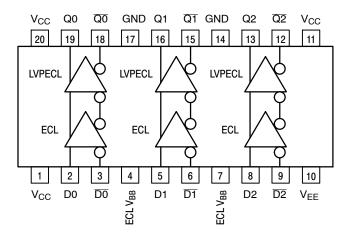


Table 1. PIN DESCRIPTION

PIN	FUNCTION
Dn, <u>Dn</u> Qn, Qn ECL V _{BB} V _{CC} V _{EE} GND	ECL Inputs LVPECL Outputs ECL Reference Voltage Output Positive Supply Negative Supply Ground

 * All V_{CC} pins are tied together on the die.

Warning: All V_{CC} , V_{EE} , and GND pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. Logic Diagram and Pinout: 20-Lead SOIC (Top View)

Table 2. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Power Supply	GND = 0 V		8 to 0	V
V_{EE}	NECL Power Supply	GND = 0 V		-8 to 0	V
V _I	NECL Mode Input Voltage	GND = 0 V	$V_I \ge V_{EE}$	-6 to 0	V
l _{out}	Output Current	Continuous Surge		50 100	mA
I _{BB}	ECL V _{BB} Sink/Source			± 0.5	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			−65 to +150	°C
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-20 WB	90 60	°C/W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-20 WB	30 to 35	°C/W
T _{sol}	Wave Solder			265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 3. NECL INPUT DC CHARACTERISTICS (V_{CC}= 3.3 V; V_{EE}= -3.3 V; GND= 0 V (Note 1))

		-40°C 2		25°C		85°C					
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	V _{EE} Power Supply Current			8.0		6.0	8.0			8.0	mA
V_{IH}	Input HIGH Voltage (Single-Ended)	-1165		-880	-1165		-880	-1165		-880	mV
V _{IL}	Input LOW Voltage (Single-Ended)	-1810		-1475	-1810		-1475	-1810		-1475	mV
ECL V _{BB}	Output Voltage Reference	-1.38		-1.26	-1.38		-1.26	-1.38		-1.26	V
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 2) Vpp < 500 mV Vpp ≥ 500 mV	V _{EE} +1.3 VEE+1.5		-0.4 -0.4	V _{EE} +1.2 VEE+1.4		-0.4 -0.4	V _{EE} +1.2 VEE+1.4		-0.4	V
I _{IH}	Input HIGH Current			150			150			150	μΑ
I _{IL}	Input LOW Current D D	0.5 -600			0.5 –600			0.5 -600			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input parameters vary 1:1 with GND. V_{EE} can vary -3.0~V to -5.5~V.
- 2. V_{IHCMR} min varies 1:1 with V_{EE} . V_{IHCMR} max varies 1:1 with GND.

Table 4. LVPECL OUTPUT DC CHARACTERISTICS (V_{CC}= 3.3 V; V_{EE}= -3.3 V; GND= 0 V (Note 1))

		-40°C 25°C									
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Icc	V _{CC} Power Supply Current			24		20	24			26	mA
V _{OH}	Output HIGH Voltage (Note 2)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
V _{OL}	Output LOW Voltage (Note 2)	1470	1605	1745	1490	1600	1680	1490	1595	1680	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Output parameters vary 1:1 with V_{CC} . V_{CC} can vary +0.5 V / -0.3 V. V_{EE} can vary -3.0 V to -5.5 V.
- 2. Outputs are terminated through a 50 Ω resistor to V_{CC} -2 volts.

Table 5. AC CHARACTERISTICS ($V_{CC} = 3.0 \text{ V}$ to 3.8 V; $V_{EE} = -3.0 \text{ V}$ to -5.5 V; GND = 0 V)

		-40°C			25°C 85°C						
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
fmax	Maximum Toggle Frequency		560			650			700		MHz
t _{PLH} t _{PHL}	Propagation Delay Diff D to Q	390		590	420		620	460		660	ps
	S.E.	340		640	370		670	410		710	Į.
t _{SKEW}	Skew Output-to-Output (Note 1) Part-to-Part (Diff) (Note 1) Duty Cycle (Diff) (Note 2)		20 25	100 200		20 25	100 200		20 25	100 200	ps
tJITTER	Random Clock Jitter		TBD			TBD			TBD		ps
V _{PP}	Input Voltage Swing (Differential Configuration) (Note 3)	150		1000	150		1000	150		1000	mV
t _r t _f	Output Rise/Fall Times Q (20% – 80%)	230		500	230		500	230		500	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Skews are valid across specified voltage range, part-to-part skew is for a given temperature.
- 2. Duty cycle skew is the difference between a TPLH and TPHL propagation delay through a device.
- 3. V_{PP} (min) is swing measured single-ended on each input in differential configuration. The device has a DC gain of ≈40.

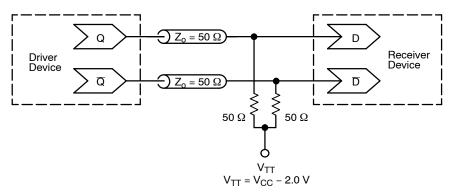


Figure 2. Typical Termination for Output Driver and Device Evaluation (See Application Note <u>AND8020/D</u> – Termination of ECL Logic Devices.)

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1672/D - The ECL Translator Guide

AND8001/D - The ECL Translator Guide

AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

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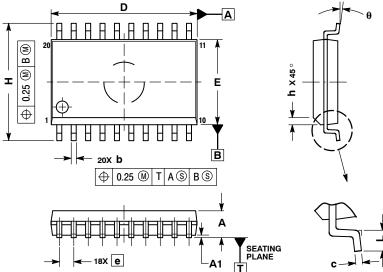




SOIC-20 WB CASE 751D-05 **ISSUE H**

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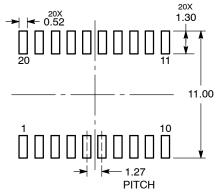
SCALE 1:1



- DIMENSIONS ARE IN MILLIMETERS.
 INTERPRET DIMENSIONS AND TOLERANCES.
- PER ASME Y14.5M, 1994.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD
- PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL

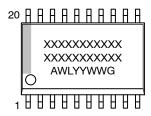
	MILLIMETERS								
DIM	MIN	MAX							
Α	2.35	2.65							
A1	0.10	0.25							
b	0.35	0.49							
С	0.23	0.32							
D	12.65	12.95							
E	7.40	7.60							
е	1.27	BSC							
Н	10.05	10.55							
h	0.25	0.75							
L	0.50	0.90							
θ	0°	7 °							

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location

WL = Wafer Lot ΥY = Year WW = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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